



# Thermal 使用说明书文档

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## 文档履历

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# 1. 概述

## 1.1 编写目的

该使用文档介绍了 thermal 的温控策略配置方法，以及调试使用说明。

## 1.2 适用范围

本文档适用于 linux4.9 内核的所有平台。

## 1.3 相关人员

本文档适用于关心系统温度及温控策略的人员

## 2. 模块介绍

### 2.1 模块功能介绍

Thermal 俗称热控制系统，其功能是通过 temperature sensor 测量当前 CPU、GPU 等设备的温度值，然后根据此温度值，影响 CPU、GPU 等设备的调频策略，对 CPU、GPU 等设备的最大频率进行限制，最终实现对 CPU、GPU 等设备温度的闭环控制，避免 SOC 温度过高。

### 2.2 相关术语介绍

Temperature sensor: 温度传感器。

Thermal: CPU 温度控制系统。

CPU: 中央处理器。

GPU: 图像处理器。

thermal zone: 将提供温度及 trip 点相关信息给 thermal core 子系统。

cooling device: thermal core 子系统通过 cooling device 对 CPU、GPU 等设备最大频率进行限制。

### 2.3 模块配置介绍

进入内核源码目录，执行 `make ARCH=arm(arm64) menuconfig` 进入配置主界面，并按以下步骤操作：

首先，进入到 Device Drivers --> Generic Thermal sysfs driver，如下图所示：

```

--- Generic Thermal sysfs driver
[*]   Expose thermal sensors as hwmon device
[*]   APIs to parse thermal data out of device tree
[ ]   Enable writable trip points
      Default Thermal governor (step_wise) --->
[ ]   Fair-share thermal governor
-*   Step_wise thermal governor
[ ]   Bang Bang thermal governor
[ ]   User_space thermal governor
[ ]   Power allocator thermal governor
[ ]   generic cpu cooling support
[ ]   Generic clock cooling support
[*]   Thermal emulation mode support
[ ]   allwinner(SUNXI) thermal drivers ---->

```

图 1: figure11.png

#### 配置项说明:

Default Thermal governor 选择, 默认为step-wise  
Thermal emulation mode support: 支持thermal模拟温度功能

Thermal cooling 配置, 进入到 Device Drivers --> Generic Thermal sysfs driver --> allwinner(SUNXI) thermal drivers --> allwinner(SUNXI) thermal cooling device drivers, 如下图所示:

```

^*^> sunxi budget cooling
^*^> sunxi budget cooling about CPU-DVFS
^*^> sunxi budget cooling about Hotplug
^> sunxi budget cooling about GPU FS

```

图 2: figure12.png

#### 配置项说明:

Sunxi budget cooling about CPU-DVFS:支持CPU DVFS功能做cooling  
 Sunxi budget cooling about Hotplug:支持CPU Hotplug功能做cooling  
 Sunxi budget cooling about GPU FS:支持gpu做cooling

进入到 Device Drivers -->Generic Thermal sysfs driver-->allwinner(SUNXI)thermal drivers-->allwinner(SUNXI)thermal sensor drivers, 进行 thermal sensor 驱动配置, 如下图所示:

```
<+> Thermal sensor driver
<+> Thermal sensor driver for SUNXI platform
```

图 3: figure13.png

配置项说明:

Thermal sensor driver:支持thermal sensor驱动  
 Thermal sensor drive for SUNXI platform:支持sunxi thermal sensor驱动

## 2.4 源码结构介绍

```
linux4.9
|-- drivers/thermal/sunxi_thermal/sunxi_thermal_sensor //thermal sensor驱动代码
|-- drivers/thermal/sunxi_thermal/sunxi_cooling_device //thermal cooling代码
```

## 3. Dts 配置

### 3.1 of-thermal

在 thermal 模块开发中，只需要将 thermal-zone、thermal Sensor、trip point、cooling Device 的关系在 DTS 文件内按照规定的格式描述，of-thermal 模块就会根据 DTS 将描述的内容自动注册，逻辑关系由 of-thermal 模块维护，使驱动代码量大大减少

```
thermal-zones{
    soc_thermal{

        polling-delay-passive=<500>;
        polling-delay=<2000>;
        thermal-sensors=<&combine0 0>;

        trips{
            cpu_trip0:t0{
                temperature=<65>;
                type="passive";
                hysteresis=<0>;
            };
            cpu_trip1:t1{
                temperature=<80>;
                type="passive";
                hysteresis=<0>;
            };
            cpu_trip2:t2{
                temperature=<90>;
                type="passive";
                hysteresis=<0>;
            };
            cpu_trip3:t3{
                temperature=<100>;
                type="passive";
                hysteresis=<0>;
            };
            gpu_trip0:t4{
                temperature=<85>;
                type="passive";
                hysteresis=<0>;
            };
            gpu_trip1:t5{
                temperature=<95>;
                type="passive";
            };
        };
    };
}
```



```

        hysteresis = <0>;
    };
    crt_trip:t6{
        temperature = <110>;
        type = "critical";
        hysteresis = <0>;
    };
};

cooling-maps{
    bind0{
        contribution = <0>;
        trip = <&cpu_trip0>;
        //cpu温度高于cpu_trip0温度点(由上面配置知道是65度),cpucooling会把cpu状态调整为state1, 由cpu_budget_cooling中的配置知道state1是1152M, 4核
        cooling-device = <&cpu_budget_cooling 1 1>;
    };
    bind1{
        contribution = <0>;
        trip = <&cpu_trip1>;
        cooling-device = <&cpu_budget_cooling 2 2>;
    };
    bind2{
        contribution = <0>;
        trip = <&cpu_trip2>;
        cooling-device = <&cpu_budget_cooling 3 4>;
    };
    bind3{
        contribution = <0>;
        trip = <&cpu_trip3>;
        cooling-device = <&cpu_budget_cooling 5 6>;
    };
    bind4{
        contribution = <0>;
        trip = <&gpu_trip0>;
        cooling-device = <&gpu_cooling 1 1>;
    };
    bind5{
        contribution = <0>;
        trip = <&gpu_trip1>;
        cooling-device = <&gpu_cooling 2 2>;
    };
};
};
};

```

Trips 为触发点的信息，包括 CPU、GPU。`crt_trip` 为 thermal 的关机触发点。

`cooling-maps` 描述了触发点与 cooling device 的绑定关系。

## 3.2 Thermal zone

```

sunxi_thermal_sensor:thermal_sensor{
    compatible = "allwinner,thermal_sensor";
    reg = <0x0 0x01c25000 0x0 0x400>;
    interrupts = <GIC_SPI 31 IRQ_TYPE_NONE>;
    clocks = <&clk_hosc>, <&clk_ths>;
    sensor_num = <3>;
    shut_temp = <120>;
    status = "okay";

    combine0:combine0{
        #thermal-sensor-cells = <1>;
        combine_cnt = <3>;
        combine_type = "max";
        combine_chn = <0 1 2>;
    };
};
    
```

sensor\_num: 表示支持的 sensor 个数。

## 3.3 Cooling device

```

cpu_budget_cooling:cpu_budget_cool{
    compatible = "allwinner,budget_cooling";
    #cooling-cells = <2>;
    status = "okay";
    state_cnt = <7>;
    cluster_num = <1>;
    state0 = <1152000 4>;
    state1 = <1104000 4>;
    state2 = <1008000 4>;
    state3 = <816000 4>;
    state4 = <648000 4>;
    state5 = <648000 2>;
    state6 = <648000 1>;
};

gpu_cooling:gpu_cooling{
    compatible = "allwinner,gpu_cooling";
    reg = <0x0 0x0 0x0 0x0>;
};
    
```

```
#cooling-cells = <2>;  
status = "okay";  
state_cnt = <4>;  
state0 = <0>;  
state1 = <456>;  
state2 = <360>;  
state3 = <144>;  
};
```

此配置，表明了 CPU/GPU 各个状态的最大频率，及最大核数值。在 trips 与 cooling device 的绑定关系里，会指明此触发点对应的状态。请参考 3.1 节的配置。

## 4. 使用说明

### 4.1 查看 sensor 温度

不同平台温度 sensor 的个数及温度监控区域 thermal\_zone 是不一样的。多个温度监控区域在/sys/class/thermal 目录下就会有多个 thermal\_zone。查看 thermal\_zone 的温度，下面以 thermal\_zone0 为例：

查看 thermal\_zone 的类型

```
#cat sys/class/thermal/thermal_zone0/type  
cpu_thermal_zone
```

查看 thermal\_zone 温度

```
#cat sys/class/thermal/thermal_zone0/temp  
36
```

### 4.2 模拟温度

thermal 有温度模拟功能，可以通过模拟温度校验温度策略是否符合预期。

设置 thermal\_zone0 的模拟温度

```
#echo 80 > /sys/class/thermal/thermal_zone0/emul_temp
```

关闭 thermal\_zone0 的模拟温度功能

```
#echo 0 > /sys/class/thermal/thermal_zone0/emul_temp
```

## 5. Declaration

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